

PIN FUNCTION DESCRIPTION

Pin	Name	Description
1	S1	Q1 Kelvin Emitter (High side switch)
2	G1	

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
SiC MOSFET			
Drain–Source Voltage	V_{DSS}	1200	V
Gate–Source Voltage	V_{GS}	+22/-10	V
Continuous Drain Current @ $T_c = 80^\circ\text{C}$ ($T_J = 175^\circ\text{C}$)	I_D	191	A
Pulsed Drain Current ($T_J = 175^\circ\text{C}$)	I_{Dpulse}	382	A
Maximum Power Dissipation @ $T_c = 80^\circ\text{C}$ ($T_J = 175^\circ\text{C}$)	P_{tot}	556	W
Minimum Operating Junction Temperature	T_{JMIN}	-40	$^\circ\text{C}$
Maximum Operating Junction Temperature	T_{JMAX}	175	$^\circ\text{C}$

NXH006P120M3F2PTHG

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
SiC MOSFET CHARACTERISTICS						
Total Gate Charge	$V_{DS} = 800 \text{ V}$, $V_{GS} = -5/20 \text{ V}$, $I_D = 100 \text{ A}$	$Q_{G(TOTAL)}$	-	622	-	nC
Gate-Source Charge		Q_{GS}	-	109	-	nC
Gate-Drain Charge		Q_{GD}	-	120	-	nC
Turn-on Delay Time	$T_J = 25 \text{ }^\circ\text{C}$ $V_{DS} = 600 \text{ V}$, $I_D = 100 \text{ A}$	$t_{d(on)}$	-	40.53	-	ns
Rise Time	$V_{GS} = -5 \text{ V} / 18 \text{ V}$, $R_G = 1$	t_r	-	13.61	-	
Turn-off Delay Time		$t_{d(off)}$	-	109	-	
Fall Time		t_f	-	8.54	-	
Turn-on Switching Loss per Pulse		E_{ON}	-	0.89	-	
Turn-off Switching Loss per Pulse		E_{OFF}	-	0.44	-	
Turn-on Delay Time	$T_J = 150 \text{ }^\circ\text{C}$ $V_{DS} = 600 \text{ V}$, $I_D = 100 \text{ A}$	$t_{d(on)}$	-	38.21	-	ns
Rise Time	$V_{GS} = -5 \text{ V} / 18 \text{ V}$, $R_G = 1$	t				

TYPICAL CHARACTERISTIC
(M1/M2 SiC MOSFET CHARACTERISTIC)

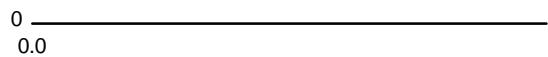


Figure 2. MOSFET Typical Output Characteristic

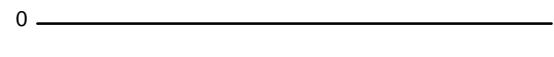


Figure 3. MOSFET Typical Output Characteristic

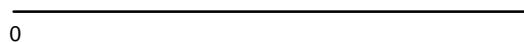


Figure 4. MOSFET Typical Transfer Characteristic

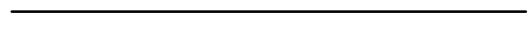


Figure 5. Body Diode Forward Characteristic



Figure 6. MOSFET R

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TYPICAL CHARACTERISTIC (M1/M2 SiC MOSFET CHARACTERISTIC)

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Figure 8. MOSFET $R_{DS(ON)}$ vs. T_j

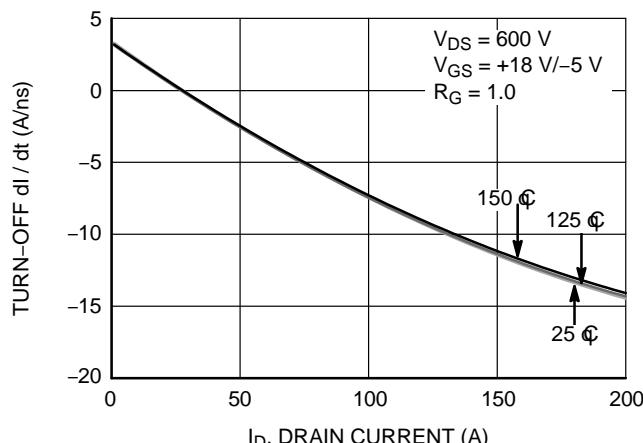
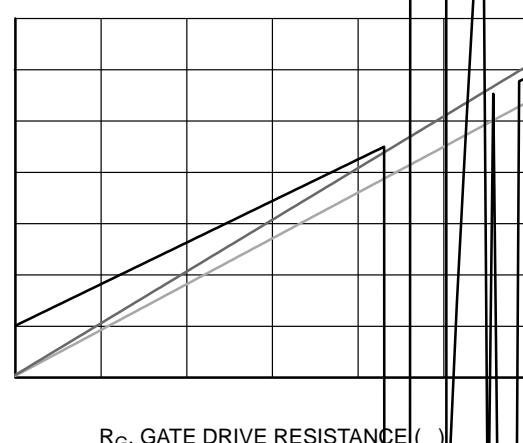
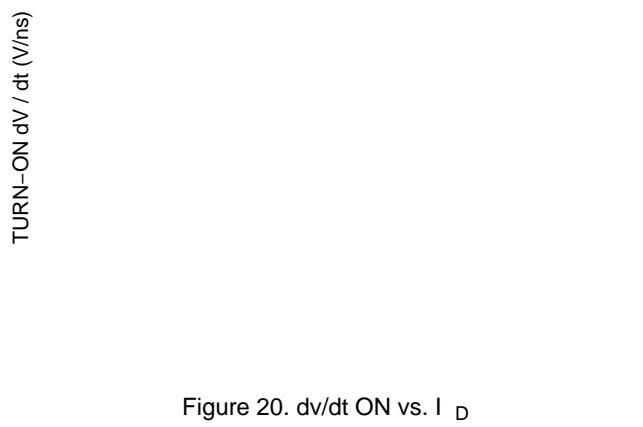
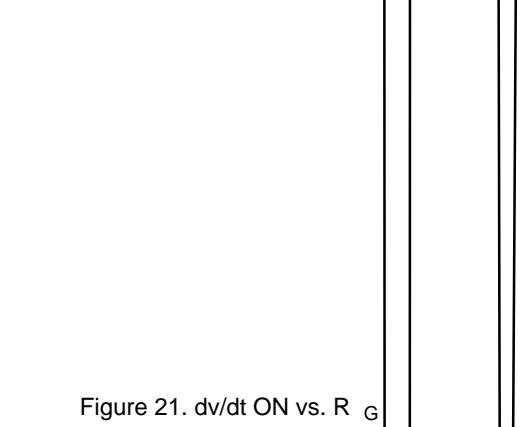
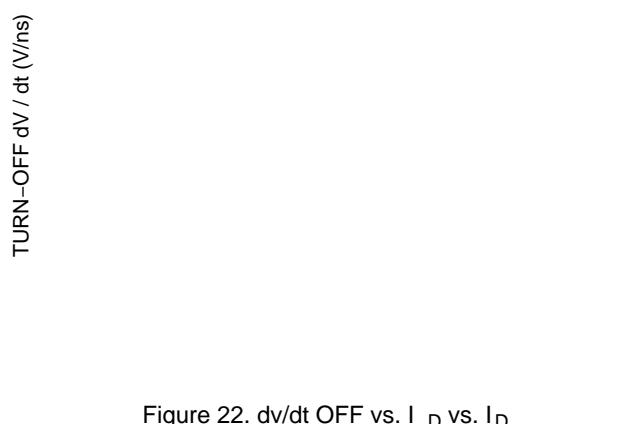
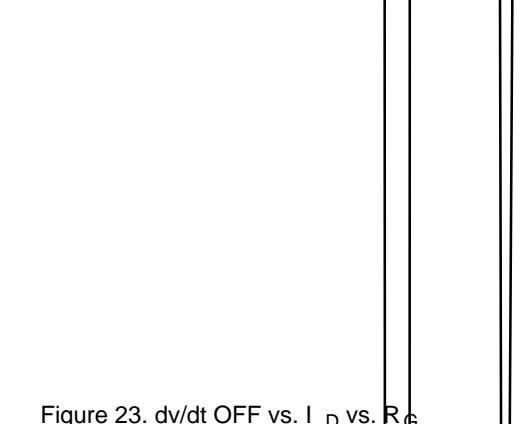
Figure 9. Gate i to i Source Voltage vs. Total Charge

Figure 10. Capacitance vs. Drain i to i Source Voltage

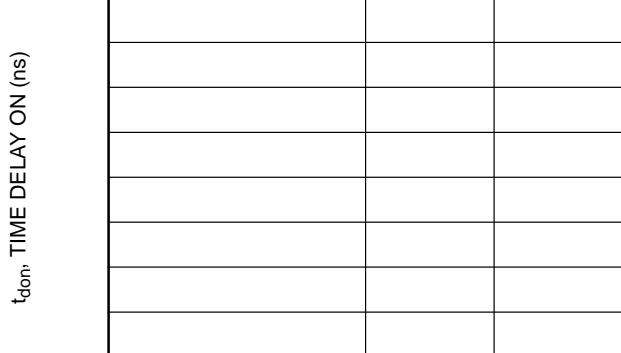
Figure 11. MOSFET Junction i to i Case Transient Thermal Impedance

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TYPICAL CHARACTERISTIC
 (M1/M1 SiC MOSFET SWITCHING CHARACTERISTIC)

Figure 18. di/dt OFF vs. I_D Figure 19. di/dt OFF vs. R_G Figure 20. dv/dt ON vs. I_D Figure 21. dv/dt ON vs. R_G Figure 22. dv/dt OFF vs. I_D vs. I_D Figure 23. dv/dt OFF vs. I_D vs. R_G

TYPICAL CHARACTERISTIC
(M1/M1 SiC MOSFET SWITCHING CHARACTERISTIC)



I_D , DRAIN CURRENT (A)

Figure 24. Typical Switching Loss t_{don} vs. I_D

R_G , GATE DRIVE RESISTANCE ()

Figure 25. Typical Switching Loss t_{don} vs. R_G



Figure 26. Typical Switching Loss t_{doff} vs. I_D

Figure 27. Typical Switching Loss t_{doff} vs. R_G



Figure 28. Typical Switching Loss t_r vs. I_D

Figure 29. Typical Switching Loss t_r vs. R_G

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